

Serial Number: 10/090,796

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Title: SHUNTING ARRANGEMENTS TO REDUCE HIGH CURRENTS IN GRID ARRAY CONNECTORS

Assignee: Intel Corporation

IN THE SPECIFICATION

Please amend the specification as follows:

The paragraph beginning on page 6, line 15 is amended as follows:

Any excessive heat must be dissipated to avoid damage, and so as to ensure a long life of the system. Heat spreader and heat sink structures are one example approach for heat dissipation, but such structures add weight and size to the system and thwart device miniaturization. Despite the ability to provide heat-dissipating heat spreaders and heat sinks to provide some heat dissipation, there still may be safety (e.g., melt down) limitation imposed on a maximum current which can be conducted through a pin/socket pair, as not all heat may be able to be conducted away. Any current over such limitation may increase a probability of damage (e.g., melt down, fire). If the disadvantageous arrangement is used in systems attempting to meet anticipated future requirements (e.g., 6 GHz processors), the maximum actual current transfer encountered per pin/socket during system operation may be a sizable percentage (e.g., 20%) over the ~~the~~ socket's current limitation. With future power current increases, this situation will only worsen.